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(71) Applicant: NEC CORP

(72) Inventor: OKADA TAKAYUKI

**(54) METHOD FOR DISCONNECTING MOUNTED COMPONENT FROM ENCLOSURE OF ELECTRONIC DEVICE, CONNECTING STRUCTURE, AND ELECTRONIC DEVICE**

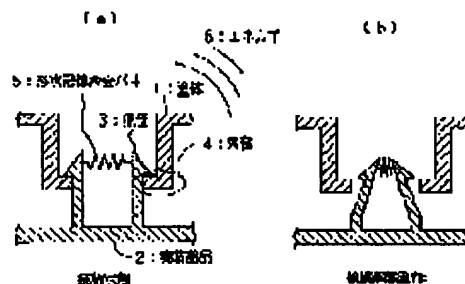
## (57) Abstract:

**PROBLEM TO BE SOLVED:** To enable a mechanical connecting means which connects a mounted component to an enclosure to cancel the mechanical connection by deforming the connecting means by heating the means by imparting energy to the means from the outside.

**SOLUTION:** A pair of pawl sections 3 fixed to a mounted component 2 is put in the hole section 4 of the enclosure 1 of an electronic device, and the pawl sections 3 are connected to each other with a spring 5 made of a shape memory alloy. Then the spring 5 is deformed to the memorized shape of the spring 5 by heating the spring 5 to a prescribed temperature by im-

parting energy 6 to the connecting structure from the outside. When the spring 5 is deformed, the spring 3 pulls the pawl sections 3 toward each other in the radial direction of the hole section 4 and disengages the sections 3 from the hole section 4. Therefore, the mounted component 2 can be separated easily from the enclosure 1 in a short time at the time of disassembling or scrapping the electronic device.

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